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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	9434
Number of Logic Elements/Cells	25000
Total RAM Bits	2002944
Number of I/O	176
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	324-LFBGA
Supplier Device Package	324-UBGA (15x15)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5ceba2u15c8n

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Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues

Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	8-input adaptive logic module (ALM) Up to 13.59 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	 Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	Requires only two core voltages to operate Available in low-cost wirebond packaging Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration



Feature	Description
	 HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight™ JTAG debug access port, trace port, and on-chip trace storage
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing (2) Partial reconfiguration (3)

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

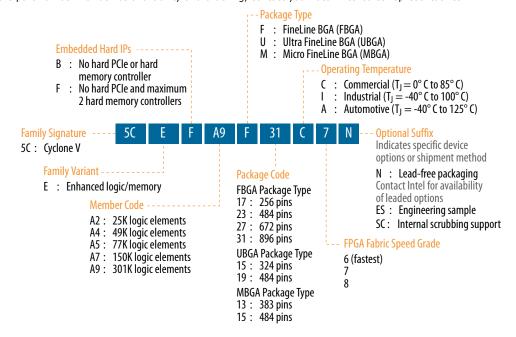
⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel® sales representatives.



Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource				Member Code		
		A2	A4	A5	A7	А9
Logic Elements	(LE) (K)	25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precisi	on DSP Block	25	66	150	156	342
18 x 18 Multipli	er	50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory C	ontroller	1	1	2	2	2

CV-51001 | 2018.05.07



Resource		Member Code					
		С3	C4	C5	С7	C9	
LVDS	Transmitter	52	84	84	120	140	
	Receiver	52	84	84	120	140	
PCIe Hard IP Block		1	2	2	2	2	
Hard Memory Controller		1	2	2	2	2	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 7. Package Plan for Cyclone V GX Devices

Member Code	M3 (11)	801 mm)	M3 (13 i		M4 (15		U3 (15		U4 (19 i	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	_	_	_	_	_	_	144	3	208	3
C4	129	4	175	6	_	_	_	_	224	6
C5	129	4	175	6	_	_	_	_	224	6
C7	_	_	_	_	240	3	_	_	240	6
C9	_	_	_	_	_	_	_	_	240	5

Member Code	F4 (23 i		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	208	3	_	_	_	_	_	_
C4	240	6	336	6	_	_	_	_
C5	240	6	336	6	_	_	_	_
C7	240	6	336	9	480	9	_	_
С9	224	6	336	9	480	12	560	12

Cyclone V GT

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

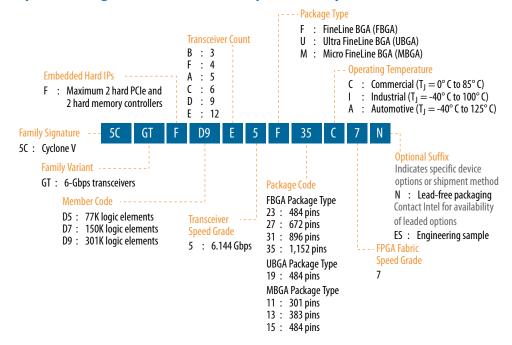
Product Selector Guide

Provides the latest information about Intel products.



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource			Member Code				
		D5	D7	D9			
Logic Elements (LE) (Logic Elements (LE) (K)		150	301			
ALM		29,080	56,480	113,560			
Register		116,320	16,320 225,920 454,240				
Memory (Kb)	M10K	4,460	6,860	12,200			
	MLAB	424	836	1,717			
Variable-precision DS	P Block	150	156	342			
18 x 18 Multiplier		300	312	684			
PLL		6	7	8			
6 Gbps Transceiver		6	9	12			
GPIO ⁽⁵⁾		336	480	560			
LVDS	Transmitter	84	120	140			
	,	•		continued			

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Maximum Resources

Table 10. **Maximum Resource Counts for Cyclone V SE Devices**

Res	ource		Me	ember Code	
		A2	A4	A5	A6
Logic Elements (LE) (K)	25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precisio	n DSP Block	36	84	87	112
18 x 18 Multiplie	18 x 18 Multiplier		168	174	224
FPGA PLL	FPGA PLL		5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
FPGA Hard Memo	ory Controller	1	1	1	1
HPS Hard Memor	ry Controller	1	1	1	1
Arm Cortex-A9 M	1PCore Processor	Single- or dual- core	Single- or dual- core	Single- or dual-core	Single- or dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Package Plan for Cyclone V SE Devices Table 11.

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)				F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	_	_
A4	66	151	145	181	_	_
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181

CV-51001 | 2018.05.07



Reso	urce	Member Code		
		D5	D6	
	Receiver	72	72	
PCIe Hard IP Block		2	2	
FPGA Hard Memory Controller		1	1	
HPS Hard Memory Controller		1	1	
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code	F896 (31 mm)				
	FPGA GPIO	HPS I/O	XCVR		
D5	288	181	9 (11)		
D6	288	181	9 (11)		

Related Information

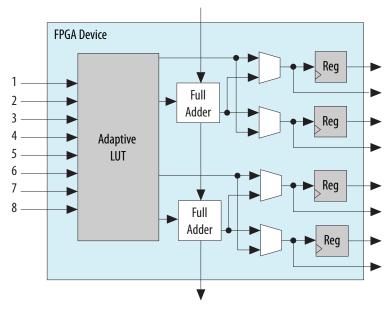
6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽¹¹⁾ If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Cyclone V Devices on page 21 Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiplyaccumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software



Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 \times 9, two 18 \times 18, or one 27 \times 27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

Table 17. Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable- precision DSP Block		dent Input and plications Ope	18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder	
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V	C3	57	171	114	57	57	57
GX	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
							continued



Variant	Member Code	Variable- precision DSP Block	•	Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Types of Embedded Memory

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Cyclone V Devices

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Member	M1	ОК	ML	Total RAM Bit	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
						continued



	Member	M10K		ML	MLAB		
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)	
Cyclone V GT	D5	446	4,460	679	424	4,884	
	D7	686	6,860	1338	836	7,696	
	D9	1,220	12,200	2748	1,717	13,917	
Cyclone V SE	A2	140	1,400	221	138	1,538	
	A4	270	2,700	370	231	2,460	
	A5	397	3,970	768	480	4,450	
	A6	553	5,530	994	621	6,151	
Cyclone V SX	C2	140	1,400	221	138	1,538	
	C4	270	2,700	370	231	2,460	
	C5	397	3,970	768	480	4,450	
	C6	553	5,530	994	621	6,151	
Cyclone V ST	D5	397	3,970	768	480	4,450	
	D6	553	5,530	994	621	6,151	

Embedded Memory Configurations

Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	×1

Clock Networks and PLL Clock Sources

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note:

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.



PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

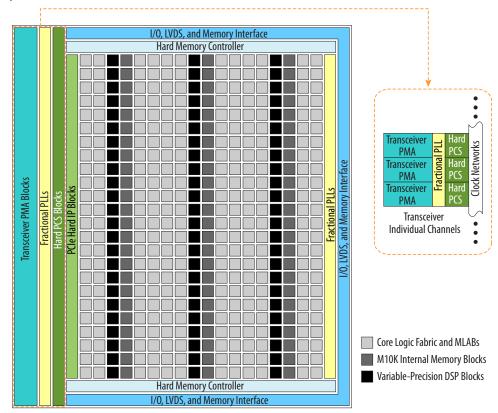
Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- \bullet LVDS output buffer with programmable differential output voltage (V $_{\text{OD}}$) and programmable pre-emphasis
- ullet On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability			
Backplane support	Driving capability up to 6.144 Gbps			
PLL-based clock recovery	Superior jitter tolerance			
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern			
Equalization and pre-emphasis	 Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization No decision feedback equalizer (DFE) 			
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps			
Input reference clock range	20 MHz to 400 MHz			
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels			



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO[®] (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	 Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾		logic	logic
GbE	1.25	Custom PHY IP core with preset feature GbE transmitter synchronization state machine	Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		
	,		continued

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

⁽¹³⁾ XAUI is supported through the soft PCS.

 $^{^{(14)}}$ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	Custom PHY IP core with preset feature Electrical idle	Custom PHY IP core with preset feature Signal detect Wider spread of asynchronous SSC
CPRI 4.1 ⁽¹⁶⁾	0.6144 to 6.144	Dedicated deterministic latency PHY IP core	Dedicated deterministic latency PHY IP core
OBSAI RP3	0.768 to 3.072	Transmitter (TX) manual bit-slip mode	Receiver (RX) deterministic latency state machine
V-by-One HS	Up to 3.75	Custom PHY IP core	Custom PHY IP core
DisplayPort 1.2 ⁽¹⁷⁾	1.62 and 2.7		Wider spread of asynchronous SSC

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

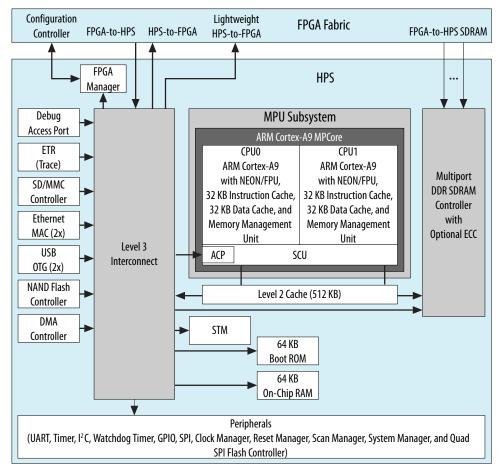
The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

⁽¹⁶⁾ High-voltage output mode (1000-BASE-CX) is not supported.

⁽¹⁷⁾ Pending characterization.



Figure 11. HPS with Dual-Core Arm Cortex-A9 MPCore Processor



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports Arm CoreSight debug and core traces to facilitate software development.



HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA®) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows
 the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily
 used for control and status register (CSR) accesses to peripherals in the FPGA
 fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

CV-51001 | 2018.05.07



Note:

Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

Cyclone V Device Family Pin Connection Guidelines

Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks[®], and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

International Altera Sales Support Offices

Dynamic and Partial Reconfiguration

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial Reconfiguration

Note:

The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support $1.8\ V$, $2.5\ V$, $3.0\ V$, and $3.3\ V$ programming voltages and several configuration schemes.

Table 24. Configuration Schemes and Features Supported by Cyclone V Devices

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion ⁽¹⁸⁾	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	_	Parallel flash
	16 bits	125	_	Yes	Yes	Yes	loader
CvP (PCIe)	x1, x2, and x4 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	-	_	_

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

⁽¹⁸⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	 Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the Sample Ordering Code and Available Options diagrams. Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to -7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	 Added descriptions to package plan tables for Cyclone V GT and ST devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.12	 Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. Updated logic elements (LE) (K) for the following devices: Cyclone V E A7: Updated from 149.5 to 150 Cyclone V GX C3: Updated from 35.5 to 36 Cyclone V GX C7: Updated from 149.7 to 150 Cyclone V GT D7: Updated from 149.5 to 150 Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: Cyclone V GX C3: Updated from 291 to 182 Cyclone V GX C4: Updated from 678 to 424 Cyclone V GX C5: Updated from 1,338 to 836 Cyclone V GX C9: Updated from 2,748 to 1,717
continued		